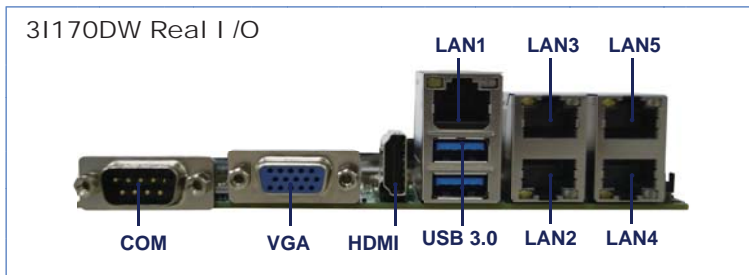


## 3I170DW Series

### Back Panel



- ▣ Intel® Skylake-S / Kaby Lake-S i7 / i5 / i3 / Celeron CPU, DDR4 Memory, VGA, HDMI, HD Audio, DI/DO  
5 x Intel Gb Ethernet, 2 x Mini PCIe,  
1 x SIM card socket, 10 x USB, 2 x COM

#### ▣ Features

- Embedded Intel® Skylake-S / Kaby Lake-S i7 / i5 / i3 / Celeron CPU, Q170 chipset
- 1 x DDR4 SODIMM socket, Max up to 16GB
- Multiple Independent display: VGA & HDMI
- 5 x Intel GbE LAN, 2 x USB 3.0, 8 x USB 2.0, 2 x COM
- 2 x Mini PCIe, 1 x SIM card socket

### Specification:

MODEL	3I170DW
CPU Type	Intel® Skylake-S / Kaby Lake-S i7 / i5 / i3 / Celeron CPU (TPD Max 35Watt)
MB Chipset	Intel® Q170 chipset
BIOS	AMI UEFI BIOS
Graphics	Intel's 9th generation (Gen 9) graphics and media encode / decode engine
System Memory	1 x DDR4 2133MHz SODIMM max up to 16GB
DVI / HDMI / DP / VGA	1 x HDMI support resolution 3840 x 2160 1 x VGA
SATA	2 x SATA ports 3.0 Data transfer rates up to 6.0 Gb/s (300 MB/s) 2 x mini card socket for mSATA
Audio	High Definition Audio Specification, Support Line-out / Mic-in
Amplifier	Two channel Class D Audio Amplifier ; 2.1W/Ch (Typ.) into a 4ΩLoad
LAN	5 x Intel (4 x I210 IT + 1 x I219LM) 10 / 100 / 1000 Mbps
IO Function	2 x RS232 / 422 / 485 (external + internal)
USB	2 x USB 3.0 (external) ; 8 x USB 2.0 (internal)
PS2 KB/MS	Internal
DIO & WDT	Hardware digital Input & Output, 8 x DI / 8 x DO Hardware Watch Dog Timer, 0~255 sec programmable
Expansion Interface	1 x Full size mini card for PCIe / mSATA / USB 1 x Half size mini card for PCIe / USB / mSATA 1 x SIM socket
Power	Wide Range DC in +9~36V
Dimension	146 x 110 mm
Operation Temperature	0 ~ 60 °C
Operation Humidity	5 ~ 95%, non-condensing